

I Claim:

1. An integrated magnetoresistive semiconductor memory,
comprising:

a plurality of memory cells, each one of said plurality of
said memory cells including a thin tunnel barrier, two
magnetic layers isolated by said tunnel barrier, and an
activatable isolating element selected from the group
consisting of a switching transistor and a diode;

integrated connecting conductors including word lines, digit
lines, bit lines and at least one line for activating said
activatable isolating element of at least one of said
plurality of said memory cells;

two metallization planes; and

a polysilicon connection plane;

each one of said connecting conductors being located in a
plane selected from the group consisting of said two
metallization planes and said polysilicon connection plane.

2. The integrated magnetoresistive semiconductor memory
according to claim 1, wherein said digit lines and said word

lines are situated in a given one of said two metallization planes.

3. The integrated magnetoresistive semiconductor memory according to claim 1, wherein said word lines are low-resistance word-lines.

4. The integrated magnetoresistive semiconductor memory according to claim 1, wherein ones of said connecting conductors that are located in said polysilicon connection plane serve as a substrate short circuit.

5. A method for fabricating an integrated magnetoresistive semiconductor memory, which comprises:

providing an integrated magnetoresistive semiconductor memory including a plurality of memory cells;

for each one of the memory cells, providing two magnetic layers that are isolated by a thin tunnel barrier;

for each one of the memory cells, providing an activatable isolating element selected from the group consisting of a switching transistor and a diode;

providing the integrated magnetoresistive semiconductor memory with integrated connecting conductors including word lines, digit lines, bit lines and lines for activating the activatable isolating element of each one of the plurality of the memory cells;

providing each one of the connecting conductors in a plane selected from the group consisting of two metallization planes and a polysilicon connection plane;

providing the digit lines in a given one of the metallization planes;

providing first lines in the given one of the metallization planes and in the polysilicon connection plane; and

using the first lines, which have not yet been used in a layout of the magnetoresistive semiconductor memory, for connecting other elements of the magnetoresistive semiconductor memory.

6. The fabrication method according to claim 5, which comprises using the given one of the metallization planes for the word lines.

7. The fabrication method according to claim 6, which comprises providing the word lines as low resistance word lines.

8. The fabrication method according to claim 5, which comprises using the polysilicon connection plane as a substrate short circuit.

10. The fabrication method according to claim 5, which comprises using the polysilicon connection plane as a substrate short circuit.